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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Kazutaka Habu, et al.

SERIAL NO: 09/066,851

FILING DATE: April 28, 1998

INVENTION: "SOLDER MATERIAL"

CASE NO.: P98,1072

GROUP ART UNIT: 1742

EXAMINER: S. Ip

J1017 U.S. PTO
10/071320
02/08/02



INFORMATION DISCLOSURE STATEMENT TRANSMITTAL LETTER

Commissioner of Patents and Trademarks
Washington, D.C. 20231

S I R:

Submitted herewith is an Information Disclosure Statement for consideration in the above-identified application. This Information Disclosure Statement is submitted:

Within three months (1) of filing date of a national application; (2) of date of entry of the national stage as set forth in 37 C.F.R. §1.491 in an international application; or (3) before the mailing date of a first Office Action on the merits, whichever occurs last. (No fee is required.)

After the mailing date of a first Office Action but before (1) mailing of a final action under 37 C.F.R. §1.113; or (2) mailing of a notice of allowance under §1.311, whichever occurs first.

Payment of the fee set forth in 37 C.F.R. §1.17(p) accompanies this submission; or

The certification specified in 37 C.F.R. §1.97(e) is made below. (No fee is required.)

After the mailing of (1) a final action under 37 C.F.R. §1.113; or (2) notice of allowance under 37 C.F.R. §1.311 whichever occurs first, but before payment of the issue fee. The certification specified in 37 C.F.R. §1.97(e) is made below. The Commissioner hereby is petitioned to consider the Information Disclosure Statement accompanying this submission. Payment for the Petition fee set forth in 37 C.F.R. §1.17(i)(1) accompanies this submission.

The undersigned counsel for applicant(s) hereby certifies each item of information identified in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this Information Disclosure Statement.

The undersigned counsel for applicant(s) hereby certifies that no item of information contained in the Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application, or to the knowledge of the undersigned, after making reasonable inquiry, was known to any individual designated in 37 C.F.R. §1.56(c) more than three months prior to the filing of the statement.

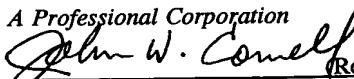
A check in the amount of \$ _____ to cover any required fee is enclosed.

The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Account No. 08-2290. *A duplicate copy of this sheet is enclosed for this purpose.*

Very respectfully,

HILL & SIMPSON

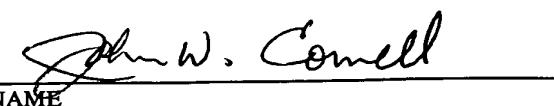
A Professional Corporation


John W. Cornell, Reg. No. 30,619

When phoning re this application,
please call (312) 876-0200.

John W. Cornell, Reg. No. 30,619
Hill & Simpson, P.C.
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I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to the Commissioner of Patents and Trademarks, Washington, D.C. 20231 on February 1, 1999.


NAME

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
INVENTORS: Kazutaka HABU; Naoko TAKEDA

ATTORNEY DOCKET NO.: 09792909-5360

SERIAL NO.: Not yet assigned GROUP ART UNIT: Not yet assigned

FILED: February 8, 2002 EXAMINER: Not yet assigned

TITLE: **"METHOD TO MANUFACTURE LEAD-FREE SOLDER MATERIAL HAVING GOOD WETTABILITY" (as amended)**

j1017 U.S. PTO
10/071320
02/08/02

IDS REQUEST AND EXPLANATION OF RELEVANCE

Assistant Commissioner for Patents
Washington, DC 20231

SIR:

In accordance with the provisions of 37 C.F.R. § 1.56, Applicant requests that citation and examination of the references identified on the attached form PTO/SB/08A-B, copies of which are enclosed herewith in accordance with 37 C.F.R. §1.98, be made during the course of examination of the above-referenced application for United States Letters Patent.

I. SUBMITTED U.S. PATENT DOCUMENTS

<u>Number</u>	<u>Patentee Name</u>	<u>Publication Date</u>
	Not applicable	

II. SUBMITTED FOREIGN PATENT DOCUMENTS

<u>Number</u>	<u>Patentee Name</u>	<u>Publication Date</u>
JP 62-230493	Masuzawa Masao, et al.	October 9, 1987
JP 8-206874	Yamaguchi Atsushi, et al.	August 13, 1996
JP 10-6075	Niha N	January 13, 1998

WO 92/17617	KRONBERG, James W.	October 15, 1992
EP 0 612 578A1	Jin, Sungho, et al.	August 31, 1994
EP 0 847 828A1	Ogashiwa, Toshinori, et al.	June 17, 1998
EP 0 710 521A1	Ninomiya, Ryuji, et al.	May 8, 1996
EP 0 639 426A1	Kawaguchi, Toranosuke, et al.	February 22, 1995
JP 09206983	Haniyu Kazutaka	August 12, 1997

III. SUBMITTED NON-PATENT LITERATURE DOCUMENTS

<u>Author</u>	<u>Article Title</u>	<u>Source Title</u>	<u>Date</u>	<u>Page(s)</u>	<u>Vol./Issue Nos.</u>	<u>Publisher</u>
<u>Publishing Location</u>						

Seiki Sakuyama, et al. "Solderability of Solder-Coated Surfaces for SMT Printed Wiring Boards" Fujitsu-Scientific and Technical Journal, vol. 29, no. 4, 21 December 1993, pages 357-366, XP000439110

Tetsuya Nakatsuka, et al. "Development of High Reliable Pb Free Solder," Production Engineering Research Laboratory, Hitachi, Ltd. Feb. 6-7, 1997, 3rd Symposium on "Microjoining Assembly Technology in Electronics"

IV. EXPLANATION OF RELEVANCE

The above items were made of record in the parent application, U.S. Serial No. 09/066,851, filed on April 28, 1998. Copies of the above items are submitted herewith.

<p>SONNENSCHEIN NATH & ROSENTHAL P.O. Box 061080 Wacker Drive Station, Sears Tower Chicago, IL 60606-1080</p> <p>Attorney Customer Number: 026263 Phn: (312) 876-8000 Fax: (312) 876-7934</p>	<p>Respectfully Submitted SONNENSCHEIN NATH & ROSENTHAL Attorneys for Applicant</p> <p>by:  David R. Metzger Reg. No. 32,919 February 8, 2002</p>
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<p>Control Number: 100000000000000000</p> <p>Substitute for form 1449A/PTO</p> <p>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</p> <p>(use as many sheets as necessary)</p>				<p>Complete if Known</p>		
<p>Application Number</p>		<p>Not yet assigned</p>				
<p>Filing Date</p>		<p>February 8, 2002</p>				
<p>First Named Inventor</p>		<p>Kazutaka HABU, et al.</p>				
<p>Art Unit</p>		<p>Not yet assigned</p>				
<p>Examiner Name</p>		<p>Not yet assigned</p>				
Sheet	1	of	2	<p>Attorney Docket Number</p> <p>9792909-5360</p>		

U.S. PATENT DOCUMENTS

FOREIGN PATENT DOCUMENTS

Examiner Initials ³	Cite No. ¹	Foreign Patent Document	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T
		Country Code ³ -Number ⁴ - Kind Code ⁵ (if known)				
		JP 62-230493	10/09/87	Masuzawa M. et al.		✓
		JP 8-206874	08/13/96	Yamaguchi, A., et al.		✓
		JP 10-6075	01/13/98	Niha, N.		✓
		WO 92/17617	10/15/92	Kronberg, J.		✓
		EP 0 612 578A1	08/31/94	Jin, S., et al.		✓
		EP 0 847828A1	06/17/98	Ogashiwa, T., et al.		✓
		EP 0 710521A1	05/08/96	Ninomiya, R., et al.		✓
		EP 0 639 426A1	02/22/95	Kawaguchi, T., et al.		✓
		JP 09206983	08/12/97	Haniyu Kazutaka		✓

Examiner Signature		Date Considered	
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Applicant's unique citation designation number (optional). ² See Kinds Codes of USPTO Patent Documents at www.uspto.gov or MPEP 901.04. ³ Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). ⁴ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁵ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. ⁶ Applicant is to place a check mark here if English language Translation is attached.

Burden Hour Statement: This form is estimated to take 2.0 hours to complete. Time will vary depending upon the needs of the individual case. Any comments on the amount of time you are required to complete this form should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, Washington, DC 20231. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Assistant Commissioner for Patents, Washington, DC 20231.

U.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE
Under the Paperwork Reduction Act of 1995, no persons are required to respond to a collection of information unless it contains a valid OMB control number.

<p>Substitute for form 1449B/PTO</p> <p>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</p> <p><i>(use as many sheets as necessary)</i></p> <p>Sheet 2 of 2</p>				<p>Complete if Known</p> <table border="1"> <tr> <td>Application Number</td> <td>Not yet assigned</td> </tr> <tr> <td>Filing Date</td> <td>February 8, 2002</td> </tr> <tr> <td>First Named Inventor</td> <td>Kazutaka HABU, et al.</td> </tr> <tr> <td>Group Art Unit</td> <td>Not yet assigned</td> </tr> <tr> <td>Examiner Name</td> <td>Not yet assigned</td> </tr> <tr> <td>Attorney Docket Number</td> <td>9792909-5360</td> </tr> </table>	Application Number	Not yet assigned	Filing Date	February 8, 2002	First Named Inventor	Kazutaka HABU, et al.	Group Art Unit	Not yet assigned	Examiner Name	Not yet assigned	Attorney Docket Number	9792909-5360
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Group Art Unit	Not yet assigned															
Examiner Name	Not yet assigned															
Attorney Docket Number	9792909-5360															

OTHER PRIOR ART -- NON PATENT LITERATURE DOCUMENTS

Examiner Signature		Date Considered	
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ Applicant's unique citation designation number (optional). ² Applicant is to place a check mark here if English language Translation is attached.

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37 CFR 1.501
 SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT
 IN A PATENT
 (use several sheets if necessary)

Docket No. P98,1072 Serial No. 09/066,851
 Applicant Kazutaka Habu, et al.
 Filing Date April 28, 1998 Group Art Unit 1742

10/07/1998
 02/08/02

U.S. PATENT DOCUMENTS							
Examiner's Initials	Document Number	Date	Name	Class	Subclass	Filing Date If appropriate	
AA							
AB							
AC							
AD							
AE							
AF							
AG							

FOREIGN PATENT DOCUMENTS							
	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
AH	JP 62-230493	Oct. 9, 1987	Japan			X	
AI	JP 8-206874	Aug. 13, 1996	Japan			X	
AJ	JP 10-6075	Jan. 13, 1998	Japan			X	
AK							
AL							

OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)

Tetsuya Nakatsuka, et al., "Development of High Reliable Pb Free Solder", Production Engineering Research Laboratory, Hitachi, Ltd., Feb. 6-7, 1997, 3rd Symposium on "Microjoining Assembly Technology in Electronics"

AM	Date Considered
AN	
AO	

Examiner

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

PTO 1449 37 CFR 1.501 INFORMATION DISCLOSURE STATEMENT IN A PATENT (use several sheets if necessary)					Docket No. P98,1072		Serial No. 09/066,851	
					Applicant Kazutaka Habu et al.			
					Filing Date April 28, 1998		Group Art Unit 1742	
U.S. PATENT DOCUMENTS								
Examiner's Initials		Document Number	Date	Name	Class	Subclass	Filing Date If appropriate	
AA								
AB								
AC								
FOREIGN PATENT DOCUMENTS								
		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
AD	WO 92/17617	/ Oct 15, 1992	PCT				X	
AE	EP 0 612 578 A1	/ Aug 31 1994	EP				X	
AF	EP 0 847 828 A1	/ June 17, 1998	EP				X	
AG	EP 0 710 521 A1	/ May 8, 1996	EP				X	
AH	EP 0 639 426 A1	/ Feb 22, 1995	EP				X	
AI	JP 09206983 (Abstract)	/ Aug 12, 1997	Japan				X	
AJ								
AK								
OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)								
	AL	Seiki Sakuyama, et al., "Solderability of Solder-Coated Surfaces for SMT Printed Wiring Boards", Fujitsu Scientific & Technical Journal, Vol. 29, No. 4, Dec. 21, 1993, pages 357-366, XP 000439110						
	AM							
	AN							
Examiner			Date Considered					
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								